

PCN Number:	20141217001	PCN Date:	12/18/2014
Title:	Qualification of Amkor Philippines as an Additional Assembly Location for Select Devices		
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037
		Dept:	Quality Services
Proposed 1st Ship Date:	03/18/2015	Estimated Sample Availability:	Date provided upon request
Change Type:			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input checked="" type="checkbox"/>		<input checked="" type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>		<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
<input type="checkbox"/>		<input type="checkbox"/>	Part number change

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of Amkor Philippines as an additional Assembly location for the devices listed below. Device construction materials differences are noted in the table below:

Package	Stats ChipPAC Korea			AP3		
	ZCU	ZCQ	ZWD	ZCU	ZCQ	ZWD
Mold compound	R003-0429C	R003-0429C	R003-0429C	1013422010	1013422010	1013422010
Mount compound	R008-0023A	R008-0052A	R008-0023A	No change	101321630	No change

Reason for Change:

Continuity of Supply. Stats ChipPAC Korea will no longer support TI production after June, 2015.


Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

<i>Assembly Site</i>		
STATS ChipPAC Korea	Assembly Site Origin (22L)	ASO: CPA
AMKOR Philippines	Assembly Site Origin (22L)	ASO: AP3

Sample product shipping label (not actual product label)



 MADE IN: Malaysia

 2DC: 2Q:

MSL '2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

 OPT:

 ITEM: 39

LBL: 5A (L)T0:1750



(1P) SN74LS07NSR

 (Q) 2000 (D) 0336

 (31T) LOT: 3959047MLA

 (4W) TKY (1T) 7523483SI2

 (P)

 (2P) REV: (V) 0033317

 (20L) CSO: SHE (21L) CCO:USA

 (22L) ASO: MLA (23L) ACO: MYS

Topside Device marking:

Assembly site code for CPA= 8

Assembly site code for AP3= 3

Product Affected		
SN0901052ZCU	TX517IZCQ	VSP2435ZWDR

Qualification Plan – Estimated completion: February, 2015		
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.		
Qualification Device: SN0901052ZCU (MSL3-260C)		
Package Construction Details		
Assembly Site:	AP3	Mold Compound: 1013422010
# Pins-Designator, Family:	289-ZCU, nFBGA	Mount Compound: R008-0023A
Solder Ball Composition:	SnAgCu	Bond Wire: 0.9 Mil Dia., Au
Qualification: <input checked="" type="checkbox"/> Plan <input type="checkbox"/> Test Results		
Reliability Test	Conditions	Sample Size / Accept
**Unbiased HAST	110C/85%RH/17.7 pps (264 Hours)	77/0
**T/C -55C/125C	-55C/+125C (700 Cyc)	77/0
Ball Bond Shear	76 balls, 3 units min	76/0
Bond Pull	76 Wire, 3 units min	76/0
Notes: **Tests require preconditioning sequence: MSL3-260C		

Qualification Plan – Estimated completion: February, 2015		
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.		
Qualification Device: TX517IZCQ (MSL 3-260C)		
Package Construction Details		
Assembly Site:	AP3	Mold Compound: 1013422010
# Pins-Designator, Family:	144-ZCQ, nFBGA	Mount Compound: 101321630
Solder Ball Composition:	SnAgCu	Bond Wire: 1.0 Mil Dia., Au
Qualification: <input checked="" type="checkbox"/> Plan <input type="checkbox"/> Test Results		
Reliability Test	Conditions	Sample Size / Fail
		Lot 1 Lot 2 Lot 3
**Unbiased HAST	110C/85%RH/17.7 pps (264 Hours)	77/0 77/0 77/0
**T/C -55C/125C	-55C/+125C (700 Cyc)	77/0 77/0 77/0
Ball Bond Shear	76 balls, 3 units min	76/0 76/0 76/0
Bond Pull	76 balls, 3 units min	76/0 76/0 76/0
Notes: **Tests require preconditioning sequence: MSL3-260C		

Qualification Plan – Estimated completion: June, 2015

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: VSP2435ZWD (MSL 2-260C)

Package Construction Details

Assembly Site:	AP3	Mold Compound:	1013422010
# Pins-Designator, Family:	100-ZWD, BGA	Mount Compound:	R008-0023A
Solder Ball Composition:	SnAgCu	Bond Wire:	1.0 Mil Dia., Au

Qualification: **Plan** **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot 3
**T/C -55C/125C	-55C/+125C (700 Cyc)	77/0	77/0	77/0
Ball Bond Shear	76 balls, 3 units min	76/0	76/0	76/0
Bond Pull	76 balls, 3 units min	76/0	76/0	76/0

Notes: **Tests require preconditioning sequence: MSL2-260C

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com